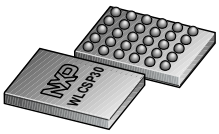


OL-TFA9897B

wafer level chip-scale package; 30 bumps; 2.06 x 2.72 x 0.525 mm (backside coating included)

8 February 2016 **Package information**

1. Package summary

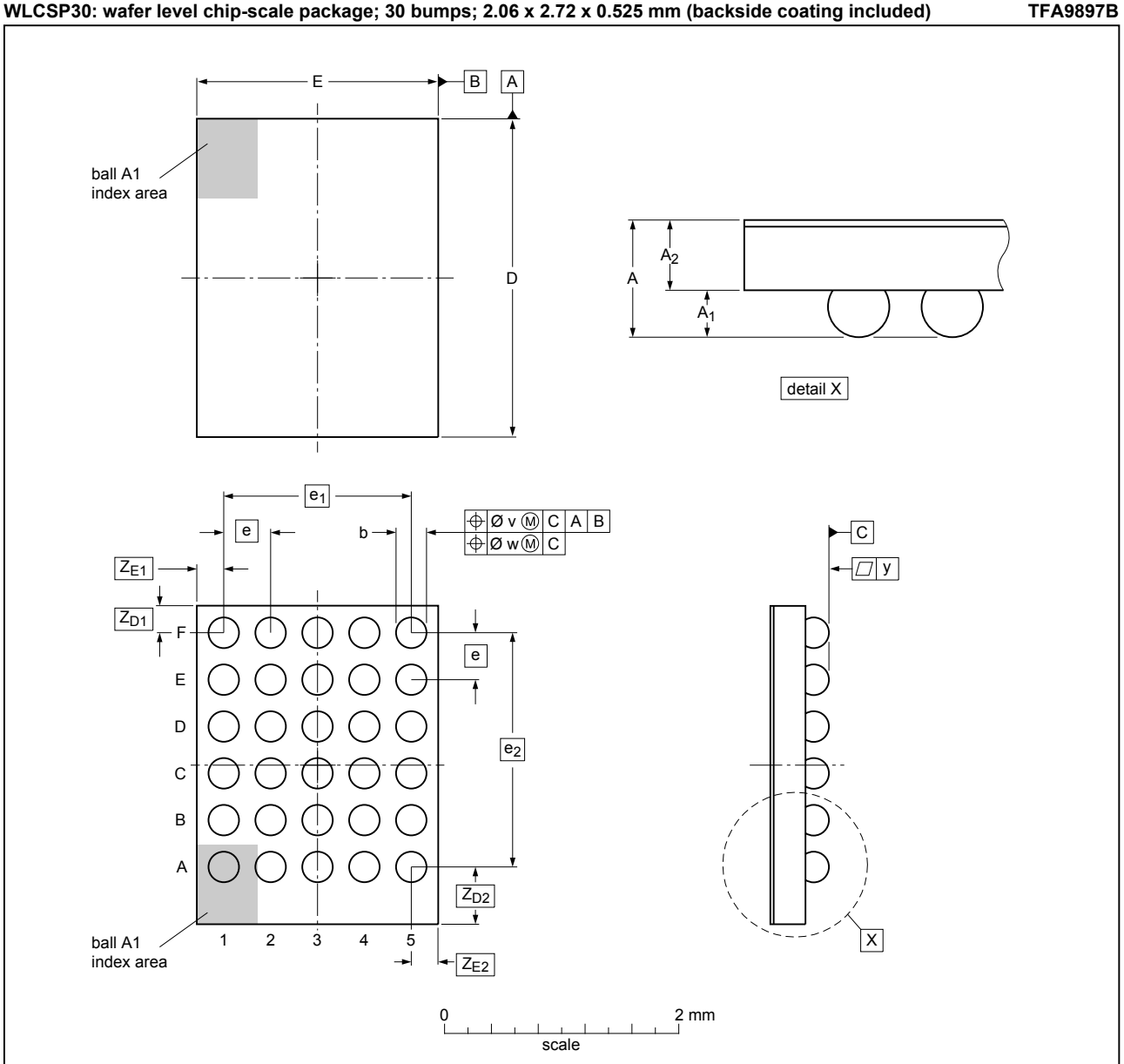
Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP30
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-3-2015

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.69	-	2.72	2.75	mm
E	package width		2.03	-	2.06	2.09	mm
A	seated height		0.485	-	0.525	0.565	mm
A_2	package height		-	-	0.33	-	mm
e	nominal pitch		-	-	0.4	-	mm
n_2	actual quantity of termination		-	-	30	-	

2. Package outline

WLCSP30: wafer level chip-scale package; 30 bumps; 2.06 x 2.72 x 0.525 mm (backside coating included) **TFA9897B**



Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	b	D	E	e	e_1	e_2	Z_{D1}	Z_{D2}	Z_{E1}	Z_{E2}	v	w	y
mm	max	0.565				2.75	2.09										
	nom	0.525	0.20	0.33	0.26	2.72	2.06	0.4	1.6	2.0	0.23	0.49	0.23	0.23	0.05	0.02	0.03
	min	0.485				2.69	2.03										

Note: Backside coating 25 µm

wlcsp30_tfa9897b_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
TFA9897B						~~15-02-13~~ 15-03-13

Fig. 1. Package outline WLCSP30 (OL-TFA9897B)

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4. Contents

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